

*A1 end*

exposing the photosensitive film according to a predetermined conductive pattern;  
forming an etching resist by removing a portion of the photosensitive film which is not exposed from the board;  
removing the patterning material from the board according to the etching resist; and  
removing the etching resist from the board, and  
the solder resist forming step comprises steps of:  
coating the surface of the board subjected to the outer layer circuit forming step with a photosensitive solder resist material;  
coating the solder resist material with a photosensitive film;  
forming a light shielding mask by irradiating a laser beam on the photosensitive film according to a formed pattern of the solder resist;  
exposing the solder resist material through a portion of the photosensitive film not irradiated by the laser beam;  
removing the light shielding mask; and  
removing the solder resist material which is not exposed due to the light shielding mask.

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5. (Amended) A method of manufacturing a multi-layer printed wiring board according to claim 1, further comprising a marking step comprising steps of:

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coating a marking position on a board surface, after the solder resist forming step, with a photosensitive marking material;  
coating the marking material with a photosensitive film;  
forming a light shielding mask by irradiating a laser beam on the marking material according to marked information;

exposing the marking material by using the light shielding mask;  
removing the light shielding mask; and  
removing the marking material which is not exposed due to the light shielding mask.

6. (Amended) A method of manufacturing a multi-layer printed wiring board according to claim 2, further comprising a marking step comprising steps of:

coating a marking position on a board surface, after the solder resist forming step, with a photosensitive marking material;

coating the marking material with a photosensitive film;

forming a light shielding mask by irradiating a laser beam on the marking material according to marked information;

exposing the marking material by using the light shielding mask;

removing the light shielding mask; and

removing the marking material which is not exposed due to the light shielding mask.

7. (Amended) A method of manufacturing a multi-layer printed wiring board according to claim 3, further comprising a marking step comprising steps of:

coating a marking position on a board surface, after the solder resist forming step, with a photosensitive marking material;

coating the marking material with a photosensitive film;

forming a light shielding mask by irradiating a laser beam on the marking material according to marked information;

exposing the marking material by using the light shielding mask;

removing the light shielding mask; and

removing the marking material which is not exposed due to the light shielding mask.

8. (Amended) A method of manufacturing a multi-layer printed wiring board according to claim 1, further comprising a marking step comprising steps of:

coating a marking position on a board surface, after the solder resist forming step, with a photosensitive marking material;

irradiating a laser beam on the marking material according to marked information; and removing the marking material except for the marking material on a portion where the marking material is hardened by irradiation of the laser beam.

9. (Amended) A method of manufacturing a multi-layer printed wiring board according to claim 2, further comprising a marking step comprising steps of:

coating a marking position on a board surface, after the solder resist forming step, with a photosensitive marking material;

irradiating a laser beam on the marking material according to marked information; and

removing the marking material except for the marking material on a portion where the marking material is hardened by irradiation of the laser beam.

10. (Amended) A method of manufacturing a multi-layer printed wiring board according to claim 3, further comprising a marking step comprising steps of:

coating a marking position on a board surface, after the solder resist forming step, with a photosensitive marking material;

irradiating a laser beam on the marking material according to marked information; and  
removing the marking material except for the marking material on a portion where the  
marking material is hardened by irradiation of the laser beam.

11. (Amended) A method of manufacturing a multi-layer printed wiring board according to  
claim 1, further comprising a marking step comprising steps of:

coating a marking position on a board surface, after the solder resist forming step, with a  
photosensitive marking material;

irradiating a laser beam on the marking material according to marked information; and  
removing the marking material except for the marking material on a portion where the  
marking material is softened by irradiation of the laser beam.

12. (Amended) A method of manufacturing a multi-layer printed wiring board according to  
claim 2, further comprising a marking step comprising steps of:

coating a marking position on a board surface, after the solder resist forming step, with a  
photosensitive marking material;

irradiating a laser beam on the marking material according to marked information; and  
removing the marking material except for the marking material on a portion where the  
marking material is softened by irradiation of the laser beam.

13. (Amended) A method of manufacturing a multi-layer printed wiring board according to  
claim 3, further comprising a marking step comprising steps of:

coating a marking coating position on a board surface, after the solder resist forming step,

with a photosensitive marking material;

irradiating a laser beam on the marking material according to marked information; and

removing the marking material except for the marking material on a portion where the marking material is softened by irradiation of the laser beam.

*And*